

N-Channel Enhancement Mode Power MOSFET

Description

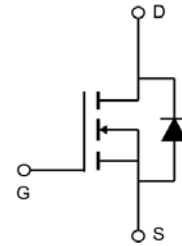
The PE6050K uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

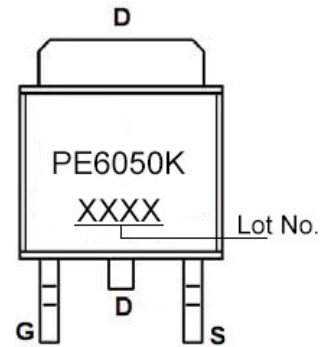
- $V_{DS} = 60V$, $I_D = 50A$
 $R_{DS(ON)} < 18m\Omega$ @ $V_{GS} = 10V$
 $R_{DS(ON)} < 22m\Omega$ @ $V_{GS} = 4.5V$
- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package

Application

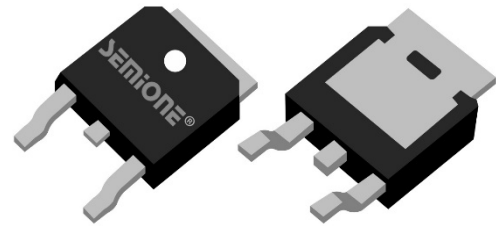
- PWM applications
- Load switch
- Power management



Schematic diagram



Marking and pin assignment



TO-252-2L

Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	50	A
Drain Current-Continuous ($T_C = 100^\circ C$)	$I_D (100^\circ C)$	35.4	A
Pulsed Drain Current	I_{DM}	200	A
Maximum Power Dissipation	P_D	85	W
Single pulse avalanche energy (Note 5)	E_{AS}	169	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	$^\circ C$

Thermal Characteristic

Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.8	$^\circ C/W$
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Electrical Characteristics ($T_c=25^{\circ}\text{C}$ unless otherwise noted)

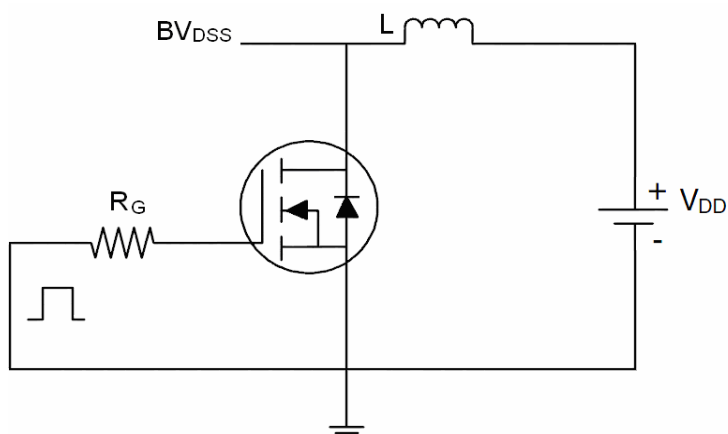
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	60	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	1.2	1.6	2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	14	18	mΩ
		V _{GS} =4.5V, I _D =20A	-	17	22	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V,I _D =20A	-	40	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{ISS}	V _{DS} =30V,V _{GS} =0V, F=1.0MHz	-	2950	-	PF
Output Capacitance	C _{OSS}		-	120	-	PF
Reverse Transfer Capacitance	C _{RSS}		-	110	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =30V, R _L =6.7Ω V _{GS} =5V,R _G =3Ω	-	15	-	nS
Turn-on Rise Time	t _r		-	20	-	nS
Turn-Off Delay Time	t _{d(off)}		-	120	-	nS
Turn-Off Fall Time	t _f		-	15.6	-	nS
Turn-on Delay Time	t _{d(on)}	V _{DD} =30V, R _L =6.7Ω V _{GS} =10V,R _G =3Ω	-	7.4	-	nS
Turn-on Rise Time	t _r		-	5.1	-	nS
Turn-Off Delay Time	t _{d(off)}		-	28.2	-	nS
Turn-Off Fall Time	t _f		-	5.5	-	nS
Total Gate Charge	Q _g	V _{DS} =30V,I _D =20A, V _{GS} =10V	-	50		nC
Gate-Source Charge	Q _{gs}		-	6		nC
Gate-Drain Charge	Q _{gd}		-	15		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =20A	-		1.2	V
Diode Forward Current (Note 2)	I _S		-	-	50	A
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF =20A	-	28	-	nS
Reverse Recovery Charge	Q _{rr}	di/dt = 100A/μs ^(Note3)	-	40	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

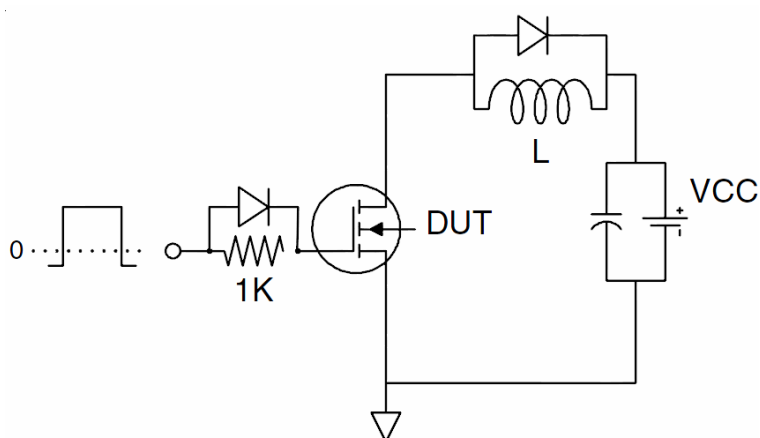
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition : $T_J=25^{\circ}\text{C}, V_{DD}=30V, V_G=10V, L=0.5mH, R_g=25\Omega$

Test Circuit

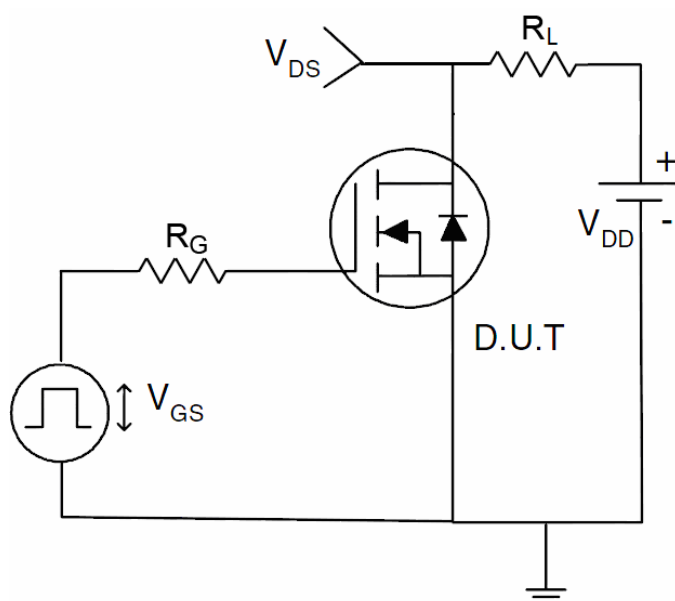
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics (Curves)

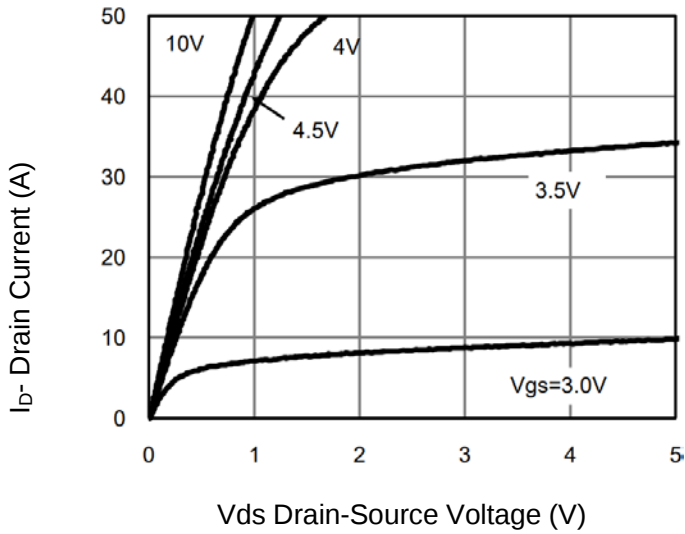


Figure 1 Output Characteristics

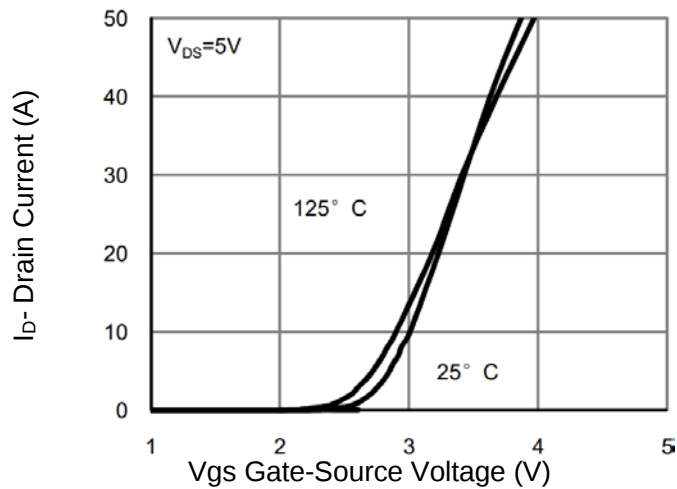


Figure 2 Transfer Characteristics

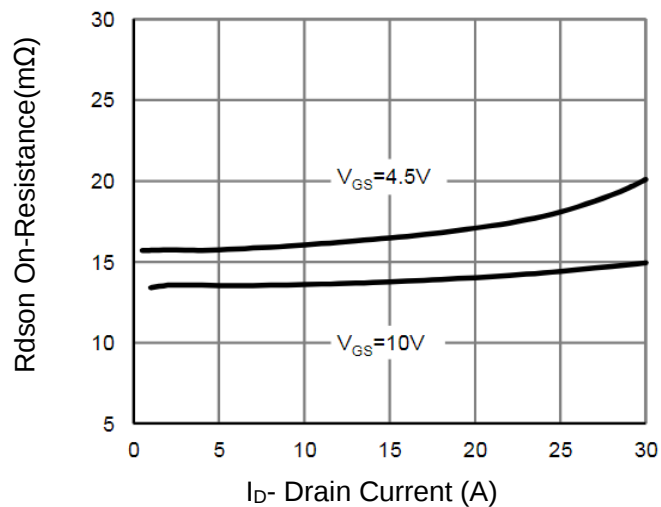


Figure 3 R_{dson} - Drain Current

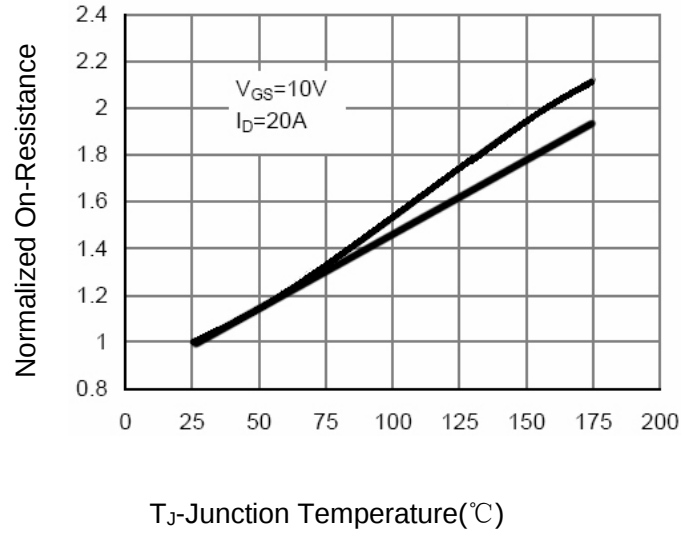


Figure 4 R_{dson} -Junction Temperature

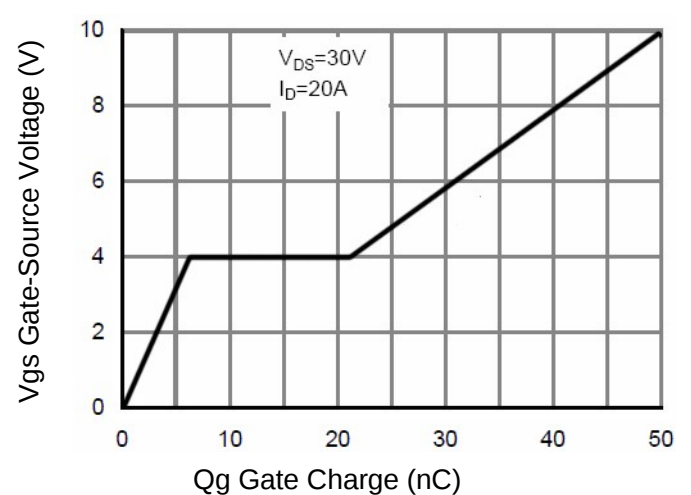


Figure 5 Gate Charge

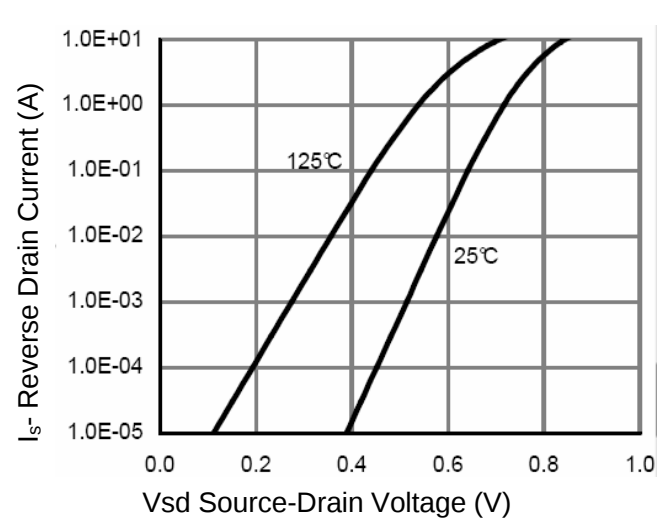


Figure 6 Source- Drain Diode Forward

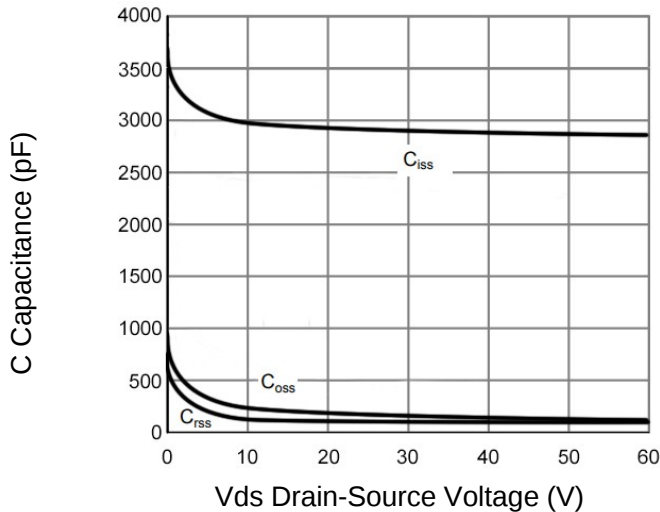


Figure 7 Capacitance vs Vds

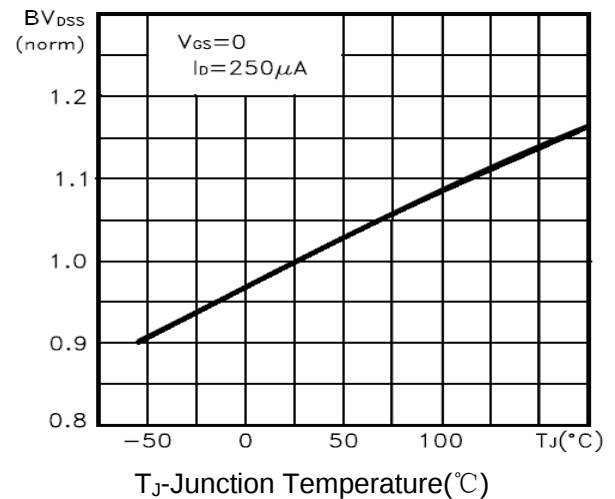


Figure 9 BV_{DSS} vs Junction Temperature

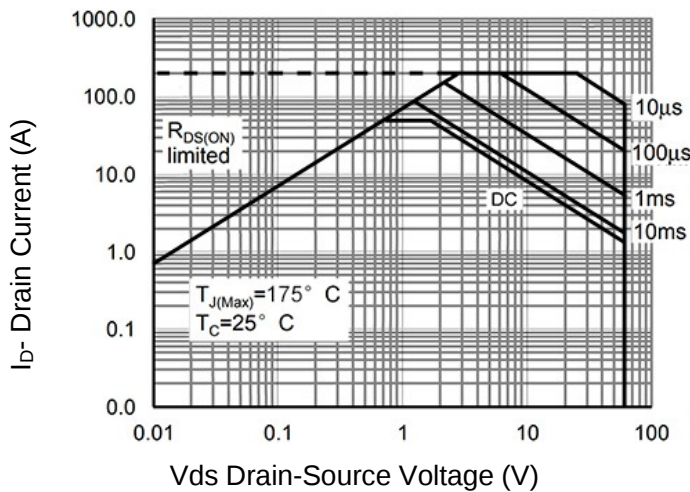


Figure 8 Safe Operation Area

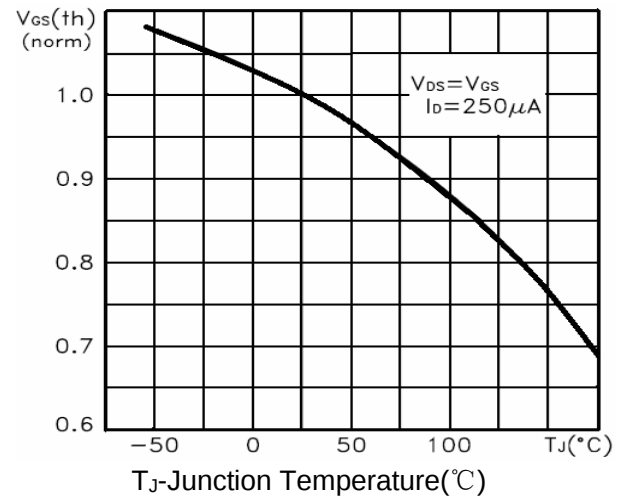


Figure 10 $V_{GS(th)}$ vs Junction Temperature

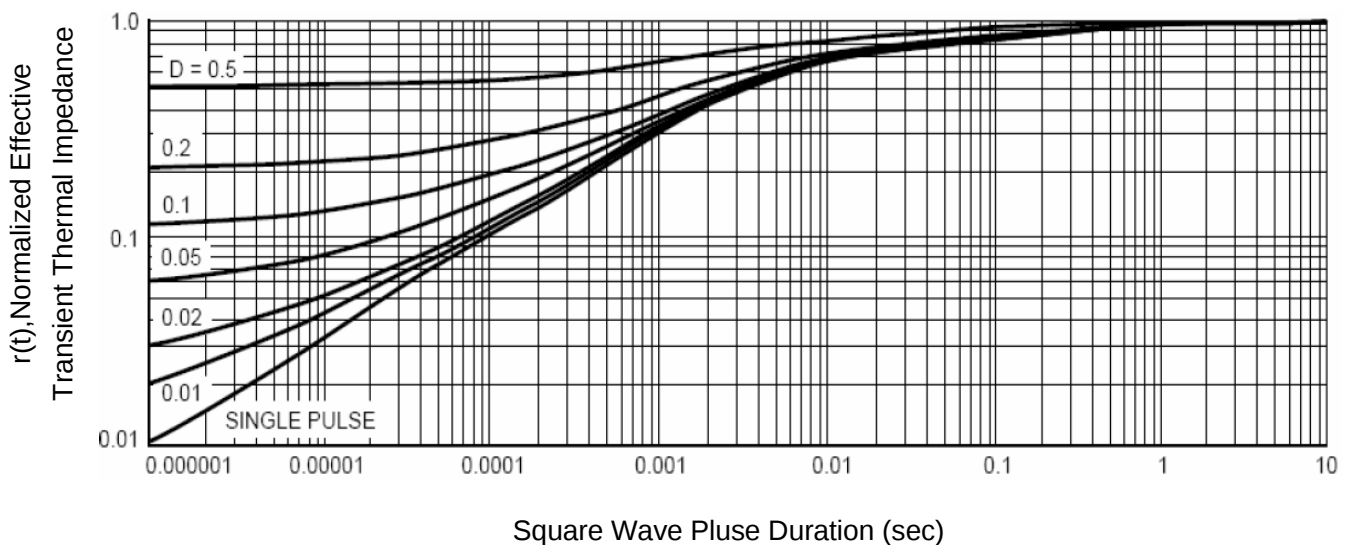
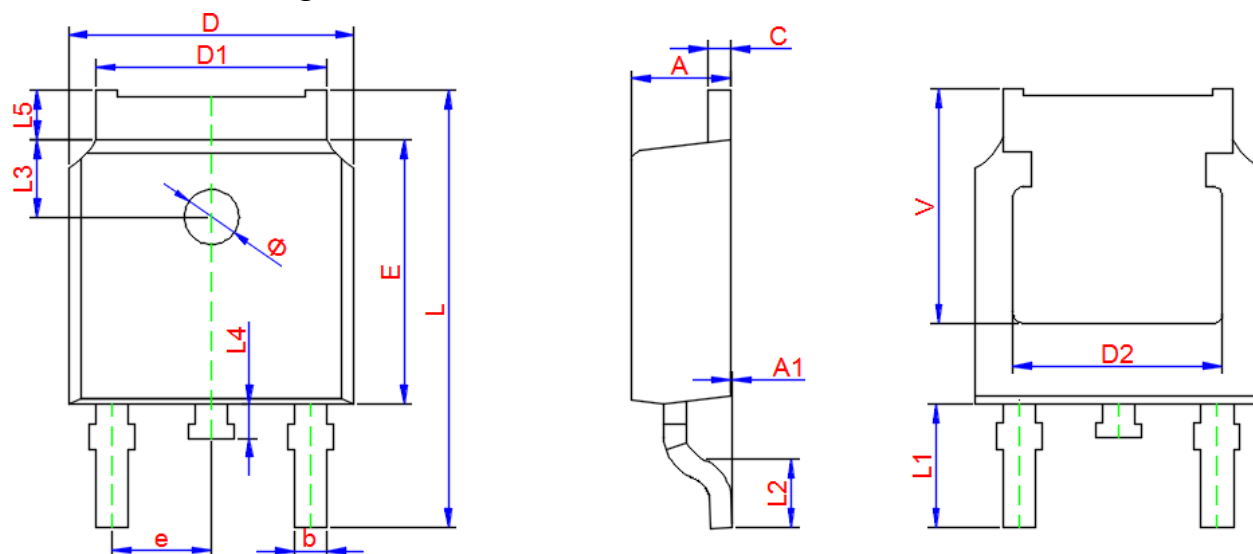


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252-2L Package Information



Symbol	Dimensions In Millimeters		
	Min.	Typ.	Max.
A	2.200	2.300	2.400
A1	0.000	- -	0.127
b	0.660	0.760	0.860
D	6.500	6.600	6.700
D1	5.100	5.330	5.460
C	0.450	0.500	0.600
D2	4.830 TYP.		
E	6.000	6.100	6.200
e	2.186	2.286	2.386
L	9.800	10.100	10.400
L1	2.900 TYP.		
L2	1.400	1.500	1.600
L3	1.800 TYP.		
L4	0.600	0.800	1.000
L5	0.900	- -	1.250
Φ	1.100.	- -	1.300
V	5.350		